IN THE SPECIFICATION

Please rewrite the passage at page 1 of the application, lines 10-17, so that it reads as follows:

~~BACKGROUND OF THE INVENTION~~

The invention is a solution/method of transferring ~~message~~ messages through a data cable, specifically, ~~the~~ standard and non-standard controlling sequences can ~~be co-existed~~ co-exist in a system to transfer ~~the~~ a defined original message under the standard controlling sequence and to transfer an extra message under a non-standard controlling sequence by ~~the system connected~~ via the data cable to communicate with the ~~correspond~~ corresponding devices. Thus, external system parameters can be monitored and controlled, and the data cable would not affect the prior communication.

A1

BACKGROUND OF THE INVENTION

Please rewrite the Abstract, on page 17 of the application, so that it reads as follows (it being noted that a clean copy of the rewritten abstract is attached to this Amendment on a separate page for the convenience of the Patent and Trademark Office):

ABSTRACT

A2

The invention provides a solution/device ~~of~~ for controlling external parameters by ~~using~~ use of the same data cable and specific software to ~~transfer / receive~~ transfer/receive messages and monitor/~~controlling~~ control external parameters in a system. Additionally, the invention is compatible with ATA/ATAPI by using ~~of~~ the ATA protocol or side-band protocol to make a main system ~~communicates~~ communicate with other device(s) through ~~original~~ an ATA/ATAPI ~~device¡¦s~~ device's data cable. Also, the invention ~~is using by~~ uses the ~~system¡¦s~~ system's data cables and a non-standard controlling sequence to transfer and receive ~~message~~ messages by the same cable to connect with the external devices for ~~monitoring/ controlling~~ monitoring/controlling

external parameters. Hence, ~~those advantages are~~ the number of data wires ~~in the invention shall be~~ needed is reduced ~~and simplified loops~~. Also, the invention can decrease the manufacture costs and get a better heating dissipation.